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PATENT
Attorney Docket No. SAM-0298

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Jae-Hak Kim, *et al.*
Serial No.: 09/994,508
Filed: November 27, 2001
Title:

Examiner: Not yet assigned
Group Art Unit: Not yet assigned

METHOD OF FABRICATING SEMICONDUCTOR DEVICES
HAVING LOW DIELECTRIC INTERLAYER INSULATION LAYER

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to the Assistant Commissioner For Patents, Washington, DC 20231.

12-12-01

Date

Vanessa Marakas
Vanessa Marakas

Assistant Commissioner for Patents
Washington, DC 20231

INFORMATION DISCLOSURE STATEMENT

Sir:

This Information Disclosure Statement is submitted:

- ☐ under 37 CFR 1.129(a), or
(First/Second submission after Final Rejection)
- ☒ under 37 CFR 1.97(b), or
(Within three months of filing national application other than a CPA under §1.53(d); or within three months of date of entry of the national stage in international application; or before mailing date of first Office Action on the merits; or before mailing date of first Office Action after filing RCE under §1.114, whichever occurs last)
- ☐ under 37 CFR 1.97(c) together with either:
- ☐ a Statement under 37 CFR 1.97(e), as checked below, or
- ☐ the \$180.00 fee under 37 CFR 1.17(p), or
(After the 37 CFR 1.97(b) time period, but before final action or notice of allowance, or other action which closes prosecution, whichever occurs first)
- ☐ under 37 CFR 1.97(d) together with:
- ☐ a Statement under 37 CFR 1.97(e), as checked below, and
- ☐ the \$180.00 fee set forth in 37 CFR 1.17(p).
(Filed after final action or notice of allowance, whichever occurs first, but before payment of the issue fee)

Applicant(s): Jae-Hak Kim, *et al.*
Serial No.: 09/994,508

Statement Under 37 1.97(e)

- ☐ Each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.
- ☐ No item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, after making reasonable inquiry, was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of this Information Disclosure Statement.

Enclosed herewith is form PTO-1449:

- ☒ Copies of cited references are enclosed.
- ☐ Copies of cited references are enclosed except those entered in prior application, U.S. Serial No. _____, and references that are not required to be submitted under 37 CFR 1.98.
- ☐ The listed references were cited in a counterpart foreign application.

Concise Explanation Requirement (non-English references):

- ☐ The "concise explanation" requirement under 36 CFR 1.98(a)(3)(i) for reference XX is satisfied by:
 - ☐ the explanation provided on the attached sheet.
 - ☐ the explanation provided in the Specification.
 - ☐ abstract.

It is requested the information disclosed herein be made of record in this application.


Applicant(s): Jae-Hak Kim, *et al.*
Serial No.: 09/994,508

Method of payment:

- ☐ Enclosed is a check in the amount of _____.
- ☐ Please charge Deposit Account of 50-1798 in the amount of _____.
- ☐ Two duplicate copies of this Statement are enclosed.
- ☒ Please charge any deficiency in fees and credit any overpayment to Deposit Account No. 50-1798.

Respectfully submitted,

Date: 12/12/01
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Sir: TRANSMITTAL LETTER

Enclosed herewith for filing in the above-identified patent application please find the following listed items:

1. Information Disclosure Statement;
2. Forms PTO-1449 and copies of cited references AR and AS ; and
3. Return Postcard.

In connection with the foregoing matter, please charge any additional fees which may be due, or credit any overpayment, to Deposit Account Number 50-1798. A duplicate copy of this letter is provided for this purpose.

Respectfully submitted,

Date: 12/12/01
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